

### **General Description**

**Applications** 

**Battery Packs** 

**Load Switches** 

Cellular & Cordless Telephones Battery-powered portable equipment

The AAT8308 is a low threshold P Channel MOS-FET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s proprietary ultrahigh density Trench technology, and space saving small outline J-lead package, performance superior to that normally found in a larger footprint has been squeezed into the area of a TSOP6 package.

#### **Features**

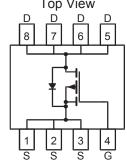
- $V_{DS(MAX)} = -20V$  $I_{D(MAX)}^{1} = -4.5A @ 25^{\circ}C$
- Low  $R_{DS(ON)}$ :

  60 mΩ @  $V_{GS}$  = -4.5V

  110 mΩ @  $V_{GS}$  = -2.5V

## **TSOPJW-8 Package**





# **Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V <sub>DS</sub>	Drain-Source Voltage		-20	- V	
$V_{GS}$	Gate-Source Voltage		±12		
I <sub>D</sub>	Continuous Drain Current @ T <sub>J</sub> =150°C ¹	T <sub>A</sub> = 25°C	±4.5		
		T <sub>A</sub> = 70°C	±3.6	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>		±24		
I <sub>S</sub>	Continuous Source Current (Source-Drain Diode) 1		-1.3		
P <sub>D</sub>	Maximum Power Dissipation <sup>1</sup>	$T_A = 25^{\circ}C$	2.0	W	
		T <sub>A</sub> = 70°C	1.3	V V	
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range		-55 to 150	°C	

### **Thermal Characteristics**

Symbol	Description	Тур	Max	Units
$R_{\theta JA}$	Junction-to-Ambient steady state 1	92	112	°C/W
R <sub>0JA2</sub>	Junction-to-Ambient t<5 seconds 1	50	62	°C/W
$R_{\theta JF}$	Junction-to-Foot 1	33	40	°C/W

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#### **Electrical Characteristics** (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units
DC Chara	DC Characteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20			V
	Drain-Source ON-Resistance <sup>2</sup>	$V_{GS}$ =-4.5V, $I_{D}$ =-4.5A		48	60	mΩ
R <sub>DS(ON)</sub>		$V_{GS}$ =-2.5V, $I_{D}$ =-3.3A		85	110	11122
I <sub>D(ON)</sub>	On-State Drain Current <sup>2</sup>	$V_{GS}$ =-4.5V, $V_{DS}$ =-5V (Pulsed)	-24			Α
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_{D}=-250\mu A$	-0.6			V
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS}$ =±12V, $V_{DS}$ =0V			±100	nA
	Drain Source Leakage Current	$V_{GS}$ =0V, $V_{DS}$ =-20V			-1	
I <sub>DSS</sub>		$V_{GS}$ =0V, $V_{DS}$ =-16V, $T_J$ =70°C <sup>3</sup>			-5	μΑ
$g_{fs}$	Forward Transconductance <sup>2</sup>	$V_{DS}$ =-5V, $I_D$ =-4.5A		7		S
Dynamic	Characteristics <sup>3</sup>					•
$Q_{G}$	Total Gate Charge	$V_{DS}$ =-10V, $R_{D}$ =2.2 $\Omega$ , $V_{GS}$ =-4.5V		7.1		
$Q_{GS}$	Gate-Source Charge	$V_{DS}$ =-10V, $R_{D}$ =2.2 $\Omega$ , $V_{GS}$ =-4.5V		1.8		nC
$Q_{GD}$	Gate-Drain Charge	$V_{DS}$ =-10V, $R_{D}$ =2.2 $\Omega$ , $V_{GS}$ =-4.5V		2.9		
t <sub>D(ON)</sub>	Turn-ON Delay	$V_{DS}$ =-10V, $V_{GS}$ =-4.5V, $R_{D}$ =2.2 $\Omega$ , $R_{G}$ =6 $\Omega$		TBD		
$t_R$	Turn-ON Rise Time	$V_{DS}$ =-10V, $V_{GS}$ =-4.5V, $R_{D}$ =2.2 $\Omega$ , $R_{G}$ =6 $\Omega$		TBD		ns
t <sub>D(OFF)</sub>	Turn-OFF Delay	$V_{DS}$ =-10V, $V_{GS}$ =-4.5V, $R_{D}$ =2.2 $\Omega$ , $R_{G}$ =6 $\Omega$		TBD		115
t <sub>F</sub>	Turn-OFF Fall Time	$V_{DS}$ =-10V, $V_{GS}$ =-4.5V, $R_{D}$ =2.2 $\Omega$ , $R_{G}$ =6 $\Omega$		TBD		
Source-D	Source-Drain Diode Characteristics					
$V_{SD}$	Source-Drain Forward Voltage <sup>2</sup>	$V_{GS}$ =0, $I_{S}$ =-4.5A			-1.3	V
Is	Continuous Diode Current <sup>1</sup>				-1.3	Α

Note 1: Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design, however  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

Note 2: Pulse test: Pulse Width = 300 μs

Note 3: Guaranteed by design. Not subject to production testing.

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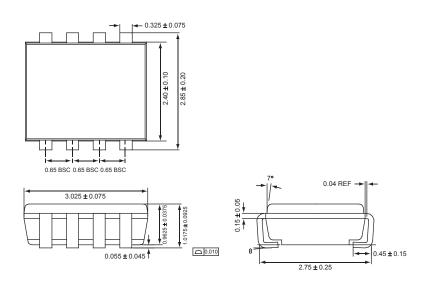


# **Ordering Information**

Package	Marking	Part Number (Tape and Reel)
TSOPJW-8		AAT8308ITS-T1

# **Package Information**

#### **TSOPJW-8**



All dimensions in millimeters.

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